

Product Change Notification / NTDO-14VNDA558

Date:

23-Aug-2022

Product Category:

Analog Multiplexer/Switch ICs

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4892 Final Notice: Qualification of UAT as a new bumping site for HV2601BD-M936, HV2701BD-M936, HV2705BD-M936 and HV2605BD-M936 catalog part numbers in 42L BMP DICE package.

Affected CPNs:

NTDO-14VNDA558_Affected_CPN_08232022.pdf NTDO-14VNDA558_Affected_CPN_08232022.csv

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of UAT as a new bumping site for HV2601BD-M936, HV2701BD-M936, HV2705BD-M936 and HV2605BD-M936 catalog part numbers in 42L BMP DICE package.

Pre and Post Change Summary:

	Pre Change	Post Change					
Bumping Location	FlipChip International (FCI)	Unisem Advance Tech (UAT)					
Solder Ball Material	SAC 266	SAC 405					
Solder Ball Pitch	600 um	600 um					
Solder Ball Size	300 um	300 um					
Polymer Material	PBO	PBO					
Polymer Thickness	4.5um	7um					
UBM Deposition Method	Sputtered	Sputtered + Plated					
UBM Thickness	Al-NiV-Cu	0.1um sputtered Ti + 0.2um sputtered Cu + 8.6um plated Cu					
UBM Opening Diameter	300 um	270 um					
RDL Deposition method	Sputtered	0.1um sputtered Ti + 0.2um sputtered Cu + 4um Plated Cu					
RDL Thickness	Ti-Al-Ti	0.1um sputtered Ti + 0.2um sputtered Cu + 4um Plated Cu					

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve productivity by qualifying UAT as a new bumping site.

Change Implementation Status:In Progress

Estimated First Ship Date:October 7, 2022 (date code: 2241)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	February 2022			>	August 2022					^	October 2022)		
Workweek	6	7	8	9	1		3	3	3	3 .	3		4	4	4	4	4
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Initial PCN Issue Date			Χ														
Qual Report										>							
Availability										^							
Final PCN Issue Date										Χ							

Estimated			'							
Implementation Date			'					^		

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:February 16, 2022: Issued initial notification.

August 23, 2022: Issued final notification. Attached Qual report. Added estimated first ship date on October 7, 2022.

Attachments:

PCN_NTDO-14VNDA558_Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

HV2601BD-M936

HV2701BD-M936

HV2705BD-M936

HV2605BD-M936

Date: Monday, August 22, 2022